IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A resin-forming mold comprising an electroconductive film having uneven portions formed on a front face thereof and made of an electroconductive metal, and an electroformed layer formed on a back face of the electroconductive film by electroforming, said electroconductive film having the front face substantially formed of aluminum and the back face formed of an electroconductive metal, wherein a compounding ratio between said aluminum and said electroconductive metal continuously changes from the front face toward the back face and in case that a resin is molded with use of the resin-forming mold, a surface layer of the electroconductive film is not peeled when the resin molded body is released from the mold after the resin is molded.

Claim 2 (Original): A resin-forming mold comprising an electroconductive film having uneven portions formed on a front face thereof and made of an electroconductive metal, and an electroformed layer formed on a back face of the electroconductive film by electroforming, said electroconductive film having the front face substantially formed of aluminum and oxygen and the back face formed of an electroconductive metal, wherein a compounding ratio between said aluminum and said electroconductive metal continuously changes from the front face toward the back face and in case that a resin is molded with use of the resin-forming mold, a surface layer of the electroconductive film is not peeled when the resin molded body is released from the mold after the resin is molded.

Claim 3 (Original): The resin-forming mold set forth in claim 1 or 2, wherein the electroconductive film comprises a material of the aluminum and the electroconductive metal in a weight compounding ratio of 70:30 to 10:90.

Claim 4 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 3~~ claim 1 or 2, wherein said electroconductive film is formed by vapor deposition.

Claim 5 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 4~~ claim 1 or 2, wherein a thickness of the electroconductive film is 200 to 3000Å.

Claim 6 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 4~~ claim 1 or 2, wherein a compounding ratio of the aluminum and the electroconductive metal is 97.5:2.5 to 10:90 in terms of a molar ratio in a depth range of 10 to 100Å from the front face of the electroconductive film.

Claim 7 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 6~~ claim 1 or 2, wherein a compounding rate of the aluminum monotonically decreases in a depth area of 110 Å or more from the front face of the electroconductive film.

Claim 8 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 2 to 7~~ claim 2, wherein at least part of the aluminum forms an oxide of aluminum through reacting with said oxygen.

Claim 9 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 8~~ claim 1 or 2, wherein the electroconductive metal is nickel.

Claim 10 (Currently Amended): The resin-forming mold set forth in ~~any one of claims 1 to 9~~ claim 1 or 2, wherein the electroformed layer is a nickel-electroformed layer formed of nickel.

Claim 11 (Original): A method for producing a resin-forming mold, comprising:

fitting aluminum to a heating heat generator inside a vacuum deposition apparatus, leaving a predetermined amount of the aluminum on the heat generator by evaporating the aluminum, fitting a master plate comprising a substrate and a photoresist film on the substrate to a substrate holder inside said vacuum deposition apparatus, said photoresist film being adapted to form a predetermined uneven pattern and fitting an electroconductive metal on said heating heat generator;

forming an electroconductive film on the photoresist film of the master plate by vacuum depositing the left aluminum and the electroconductive metal;

forming an electroformed layer on the electroconductive film by electroforming an electroforming metal; and

obtaining the resin-forming mold by removing the master plate from the electroconductive film.

Claim 12 (Original): The method for producing the resin-forming mold set forth in claim 11, wherein a weight compounding ratio between the left aluminum and the fitted electroconductive metal is in a range of 90:10 to 10:90.

Claim 13 (Currently Amended): The method for producing the resin-forming mold set forth in claim 11 ~~or 12~~, wherein a thickness of the electroconductive film is 200 to 3000Å.

Claim 14 (Currently Amended): The method for producing the resin-forming mold set forth in ~~any of claims 11 to 13~~ claim 11, wherein the electroconductive metal is nickel

Claim 15 (Currently Amended): The method for producing the resin-forming mold set forth in ~~any of claims 11 to 13~~ claim 11, wherein the metal to be electroformed is nickel.